MA6X718 (MA718)

Silicon epitaxial planar type

For switching

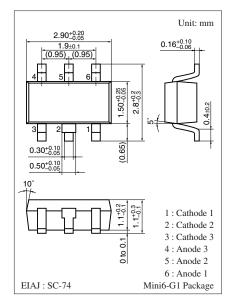
For wave detection

Features

- Three isolated elements are contained in one package, allowing high-density mounting
- Two MA3X704A (MA704A) is contained in one package (of a type in the same direction)
- Forward voltage V_F, optimum for low voltage rectification
- \bullet Optimum for high frequency rectification because of its short reverse recovery time $t_{\rm rr}$

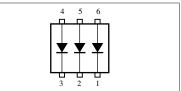
Parameter	Symbol	Rating	Unit
Reverse voltage	V _R	30	V
Peak forward current *	I _{FM}	150	mA
Forward current *	I _F	30	mA
Junction temperature	Tj	125	°C
Storage temperature	T _{stg}	-55 to +125	°C

Absolute Maximum Ratings $T_a = 25^{\circ}C$



Marking Symbol: M2N

Internal Connection



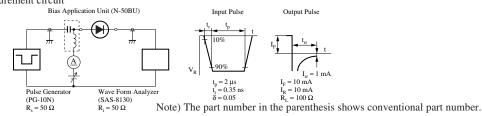
Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$		± 3°C	3 2 1				
Parameter	Symbol	Conditions	Min	Тур	Max	Unit	
Forward voltage	V _{F1}	$I_F = 1 mA$			0.4	V	
	V _{F2}	$I_F = 30 \text{ mA}$			1.0		
Reverse current	I _R	$V_R = 30 V$			1	μΑ	
Terminal capacitance	Ct	$V_R = 1 V, f = 1 MHz$		1.5		pF	
Reverse recovery time *	t _{rr}	$I_F = I_R = 10 \text{ mA}$		1.0		ns	
		I_{rr} = 1 mA , R_L = 100 Ω					
Detection efficiency	η	$V_{IN} = 3 V_{(peak)}$, f = 30 MHz		65		%	
		$R_L = 3.9 \text{ k}\Omega, C_L = 10 \text{ pF}$					

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

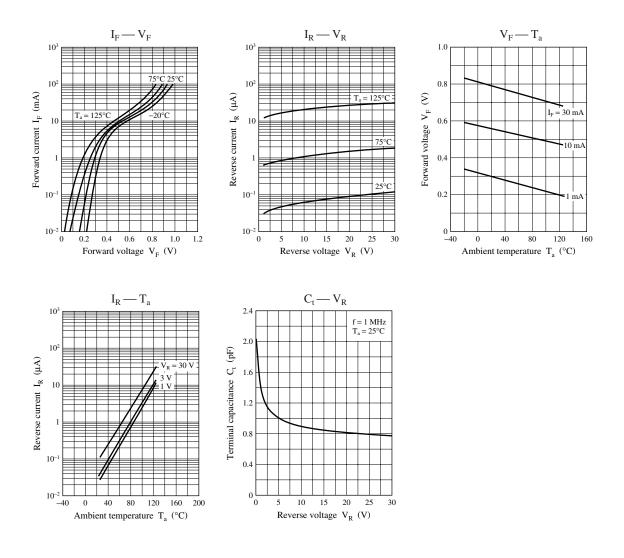
2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.

- 3. Absolute frequency of input and output is 2 GHz.
- 4. *: t_{rr} measurement circuit

Note) *: Value for single diode



Panasonic



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